Brocken 4 - High-performance 220W TDP single tower for sophisticated systems

Matt black surface coating, 6x6mm heatpipes, large asymmetric heatsink and an aerodynamically optimised fin design - Brocken 4 combines pure performance with almost silent operation even in demanding systems.

JetStream fans
Our brand new JetStream fans set new standards in our Alpenföhn portfolio! The fan has an airflow-optimised impeller, a modified frame and next-gen bearings, which ensure excellent running smoothness during maximum performance. The JetStream's anti vibration pads reduce vibrations to a minimum.

Specifications
Brocken 4

Part number	84000000205
Dimensions	127x119x155 mm
Weight	1098 g (incl. fan)
Heatpipes	6 x 6 mm
Fins	Aluminium
Baseplate	Copper
Compatibility AMD	AM5, AM4
Compatibility Intel	1700, 1200, 115X, 20XX
Thermal Grease	Inclusive

Specifications
JetStream

Dimensions	120x120x27 mm
Rated Voltage	12 VDC
Voltage Range	5 - 13,2 VDC
Bearing	Hydraulic Bearing
Fan Connector	4-Pin PWM
Airflow	94 m³/h
Speed	400 - 1600 RPM
Noise	22,8 dB(A)
Pressure	1,74 mm H2O
Rated Current	0,15 A
Input Power	1,8 W
Lifespan @ 25° C	up to 300.000 h

Matt black Surface coating
The entire heatsink of the Brocken 4 is coated in classy matt black. Black is beautiful – do you agree?

High-end heat pipes & copper base plate
The 6 high-end heat pipes are connected to the nickel-plated copper base plate over a large area, which ensures that the heat from the CPU is effectively absorbed. This enables the heat pipes to transport the heat of the processor quickly and efficiently to the large-area heat sink.

Asymmetrical heat sink
The asymmetrical design of the Brocken 4 gives you maximised flexibility in the selection of RAM modules. No matter how high the heat spreader of the module may be - it fits without any problems! 100% RAM compatibility on sockets 1700, 1200, 115X, AM5 and AM4.

Expandable fan assembly
For even more performance, the scope of delivery includes additional fan clamps and decoupling elements. This means you can easily add an additional 120 mm fan to the other side of the heatsink and increase the cooling performance even more.

Thermal compound
The high-performance thermal compound has excellent thermal conductivity. Advantages: No curing, silicone-free and not electrically conductive.

German Engineering
Our innovative use of materials and the new Rock Mount 3 mounting system create the perfect balance between performance and compatibility.

Compatibility
The included Rock Mount 3 mounting system offers a secure connection to the sockets:
Intel® LGA: 1700, 1200, 115X, 20XX
AMD: AM5, AM4